HM5116100 Series

16 M FP DRAM (16-Mword × 1-bit)
4 k Refresh

HITACHI

ADE-203-646E (Z)
Rev. 5.0
Nov. 1997

Description

The Hitachi HM5116100 is a CMOS dynamic RAM organized 16,777,216-word × 1-bit. It employs the most advanced 0.5µm CMOS technology for high performance and low power. The HM5116100 offers Fast Page Mode as a high speed access mode. It is packaged in 26-pin plastic SOJ.

Features

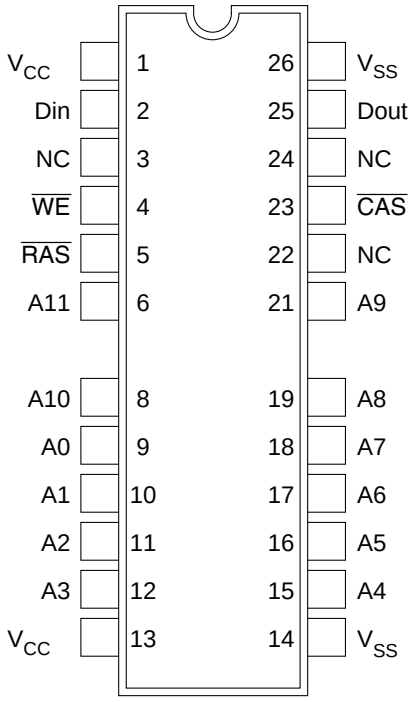
- Single 5 V (±10%)
- Access time: 60 ns/70 ns (max)
- Power dissipation
  - Active mode: 440 mW/385 mW (max)
  - Standby mode 11 mW (max)
- Fast page mode capability
- Refresh cycles
  - 4096 refresh cycles : 64 ms
- 3 variations of refresh
  - $\overline{\text{RAS}}$-only refresh
  - $\overline{\text{CAS}}$-before-$\overline{\text{RAS}}$ refresh
  - Hidden refresh
- Test function
  - 16-bit parallel test mode

Ordering Information

Type No.	Access time	Package
HM5116100S-6	60 ns	300-mil 26-pin plastic SOJ (CP-26/24DB)
HM5116100S-7	70 ns	

Pin Arrangement

HM5116100S Series

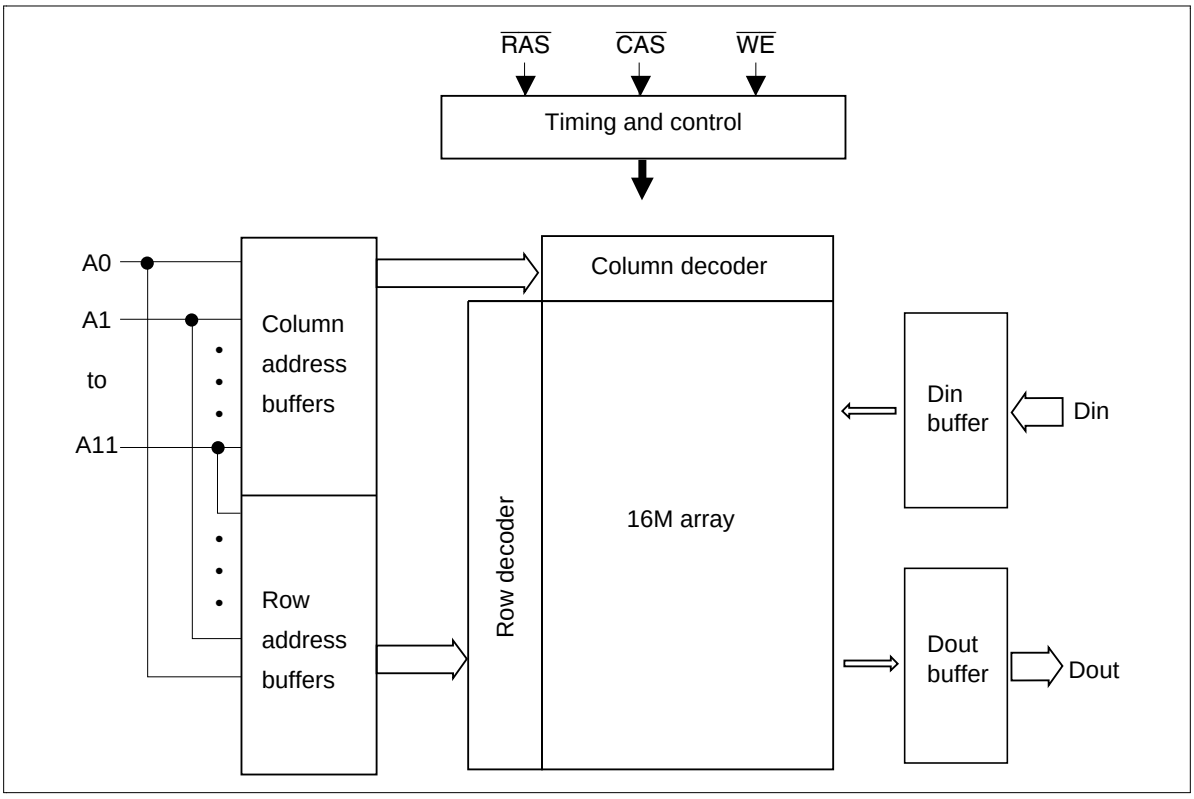


(Top view)

Pin Description

Pin name	Function
A0 to A11	Address input • Row/Refresh A0 to A11 • Column A0 to A11
Din	Data input
Dout	Data output
$\overline{RAS}$	Row address strobe
$\overline{CAS}$	Column address strobe
$\overline{WE}$	Read/write enable
V_{CC}	Power supply
V_{SS}	Ground
NC	No connection

Block Diagram



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	–1.0 to +7.0	V
Supply voltage relative to V_{SS}	V_{CC}	–1.0 to +7.0	V
Short circuit output current	Iout	50	mA
Power dissipation	P_T	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	–55 to +125	°C

Recommended DC Operating Conditions (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply voltage	V_{CC}	4.5	5.0	5.5	V	1
Input high voltage	V_{IH}	2.4	—	6.5	V	1
Input low voltage	V_{IL}	–1.0	—	0.8	V	1

Note: 1. All voltage referred to V_{SS}

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V ± 10%, V_{SS} = 0 V)

		HM5116100					
		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Test conditions**
Operating current[*1, *2]	I_{CC1}	—	80	—	70	mA	t_{RC} = min
Standby current	I_{CC2}	—	2	—	2	mA	TTL interface $\overline{RAS}$, $\overline{CAS}$ = V_{IH} Dout = High-Z
		—	1	—	1	mA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2V Dout = High-Z
$\overline{RAS}$-only refresh current[*2]	I_{CC3}	—	80	—	70	mA	t_{RC} = min
Standby current[*1]	I_{CC5}	—	5	—	5	mA	$\overline{RAS}$ = V_{IH}, $\overline{CAS}$ = V_{IL} Dout = enable
$\overline{CAS}$-before-$\overline{RAS}$ refresh current	I_{CC6}	—	80	—	70	mA	t_{RC} = min
Fast page mode current[*1, *3]	I_{CC7}	—	70	—	60	mA	t_{PC} = min
Input leakage current	I_{LI}	–10	10	–10	10	µA	0 V ≤ Vin ≤ 7 V
Output leakage current	I_{LO}	–10	10	–10	10	µA	0 V ≤ Vout ≤ 7 V Dout = disable
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = –5 mA
Output low voltage	V_{OL}	0	0.4	0	0.4	V	Low Iout = 4.2 mA

Notes: 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.
2. Address can be changed once or less while $\overline{RAS}$ = V_{IL}.
3. Address can be changed once or less while $\overline{CAS}$ = V_{IH}.

Capacitance (Ta = 25°C, V_{CC} = 5 V ± 10%)

Parameter	**Symbol**	**Typ**	**Max**	**Unit**	**Notes**
Input capacitance (Address, Data-in)	C_{I1}	—	5	pF	1
Input capacitance (Clocks)	C_{I2}	—	7	pF	1
Output capacitance (Data-out)	C_O	—	7	pF	1, 2

Notes: 1. Capacitance measured with Booton Meter or effective capacitance measuring method.
2. $\overline{CAS}$ = V_{IH} to disable Dout.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V ±10%, V_{SS} = 0 V)[*1, *2, *16]

Test Conditions

- Input rise and fall time : 5 ns
- Input timing reference levels : 0.8 V, 2.4 V
- Output load : 2 TTL gate + C_L (100 pF) (Including scope and jig)

Read, Write, Read-Modify-Write and Refresh Cycles (Common parameters)

		HM5116100					
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Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Random read or write cycle time	t_{RC}	110	—	130	—	ns	
$\overline{RAS}$ precharge time	t_{RP}	40	—	50	—	ns	
$\overline{CAS}$ precharge time	t_{CP}	10	—	10	—	ns	
$\overline{RAS}$ pulse width	t_{RAS}	60	10000	70	10000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	15	10000	18	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	ns	
Row address hold time	t_{RAH}	10	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	ns	
Column address hold time	t_{CAH}	10	—	15	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	20	45	20	52	ns	3
$\overline{RAS}$ to column address delay time	t_{RAD}	15	30	15	35	ns	4
$\overline{RAS}$ hold time	t_{RSH}	15	—	18	—	ns	
$\overline{CAS}$ hold time	t_{CSH}	60	—	70	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	5	—	5	—	ns	
Transition time (rise and fall)	t_T	3	50	3	50	ns	5

Read Cycle

		HM5116100					
		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Access time from $\overline{RAS}$	t_{RAC}	—	60	—	70	ns	6, 7, 17
Access time from $\overline{CAS}$	t_{CAC}	—	15	—	18	ns	7, 8, 15, 17
Access time from address	t_{AA}	—	30	—	35	ns	7, 9, 15, 17
Read command setup time	t_{RCS}	0	—	0	—	ns	
Read command hold time to $\overline{CAS}$	t_{RCH}	0	—	0	—	ns	10
Read command hold time to $\overline{RAS}$	t_{RRH}	0	—	0	—	ns	10
Column address to $\overline{RAS}$ lead time	t_{RAL}	30	—	35	—	ns	
Column address to $\overline{CAS}$ lead time	t_{CAL}	30	—	35	—	ns	
$\overline{CAS}$ to output in low-Z	t_{CLZ}	0	—	0	—	ns	
Output data hold time	t_{OH}	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	15	—	15	ns	11

Write Cycle

		HM5116100					
		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Write command setup time	t_{WCS}	0	—	0	—	ns	12
Write command hold time	t_{WCH}	10	—	15	—	ns	
Write command pulse width	t_{WP}	10	—	10	—	ns	
Write command to $\overline{RAS}$ lead time	t_{RWL}	15	—	18	—	ns	
Write command to $\overline{CAS}$ lead time	t_{CWL}	15	—	18	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	ns	13
Data-in hold time	t_{DH}	10	—	15	—	ns	13

Read-Modify-Write Cycle

		HM5116100					
		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Read-modify-write cycle time	t_{RWC}	130	—	153	—	ns	
$\overline{RAS}$ to $\overline{WE}$ delay time	t_{RWD}	60	—	70	—	ns	12
$\overline{CAS}$ to $\overline{WE}$ delay time	t_{CWD}	15	—	18	—	ns	12
Column address to $\overline{WE}$ delay time	t_{AWD}	30	—	35	—	ns	12

Refresh Cycle

		HM5116100					
		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
$\overline{CAS}$ setup time (CBR refresh cycle)	t_{CSR}	5	—	5	—	ns	
$\overline{CAS}$ hold time (CBR refresh cycle)	t_{CHR}	10	—	10	—	ns	
$\overline{WE}$ setup time (CBR refresh cycle)	t_{WRP}	0	—	0	—	ns	
$\overline{WE}$ hold time (CBR refresh cycle)	t_{WRH}	10	—	10	—	ns	
$\overline{RAS}$ precharge to $\overline{CAS}$ hold time	t_{RPC}	5	—	5	—	ns	

Fast Page Mode Cycle

		HM5116100					
		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Fast page mode cycle time	t_{PC}	40	—	45	—	ns	
Fast page mode $\overline{RAS}$ pulse width	t_{RASP}	—	100000	—	100000	ns	14
Access time from $\overline{CAS}$ precharge	t_{CPA}	—	35	—	40	ns	7, 15, 17
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{CPRH}	35	—	40	—	ns	

Fast Page Mode Read-Modify-Write Cycle

		HM5116100					
		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Fast page mode read-modify-write cycle time	t_{PRWC}	60	—	68	—	ns	
$\overline{WE}$ delay time from $\overline{CAS}$ precharge	t_{CPW}	35	—	40	—	ns	12

Test Mode Cycle *[16]

		HM5116100					
		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Test mode $\overline{WE}$ setup time	t_{WTS}	0	—	0	—	ns	
Test mode $\overline{WE}$ hold time	t_{WTH}	10	—	10	—	ns	

Refresh Cycle

Parameter	**Symbol**	**Max**	**Unit**	**Note**
Refresh period	t_{REF}	64	ms	4096 cycles

Notes:
1. AC measurements assume t_T = 5 ns.
2. An initial pause of 200 μs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{RAS}$-only refresh or $\overline{CAS}$-before-$\overline{RAS}$ refresh). If the internal refresh counter is used, a minimum of eight $\overline{CAS}$-before-$\overline{RAS}$ refresh cycles are required.
3. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
4. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA}.
5. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
6. Assume that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
7. Measured with a load circuit equivalent to 2 TTL loads and 100 pF.
8. Assume that $t_{RCD} \geq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max).
9. Assume that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \geq t_{RAD}$ (max).
10. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
11. t_{OFF} (max) and t_{OEZ} (max) define the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
12. t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD}$ (min), $t_{CWD} \geq t_{CWD}$ (min), and $t_{AWD} \geq t_{AWD}$ (min), or $t_{CWD} \geq t_{CWD}$ (min), $t_{AWD} \geq t_{AWD}$ (min) and $t_{CPW} \geq t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
13. These parameters are referenced to $\overline{CAS}$ leading edge in early write cycles and to $\overline{WE}$ leading edge in delayed write or read-modify-write cycles.
14. t_{RASP} defines $\overline{RAS}$ pulse width in fast page mode cycles.
15. Access time is determined by the longest among t_{AA}, t_{CAC} and t_{CPA}.
16. The 16M DRAM offers a 16-bit time saving parallel test mode. Address CA0, CA1, CA10 and CA11 for the 16M × 1 are don't care during test mode. Test mode is set by performing a $\overline{WE}$-and-$\overline{CAS}$-before-$\overline{RAS}$ (WCBR) cycle. In 16-bit parallel test mode, data is written into 16 bits in parallel at Din and read out from Dout.

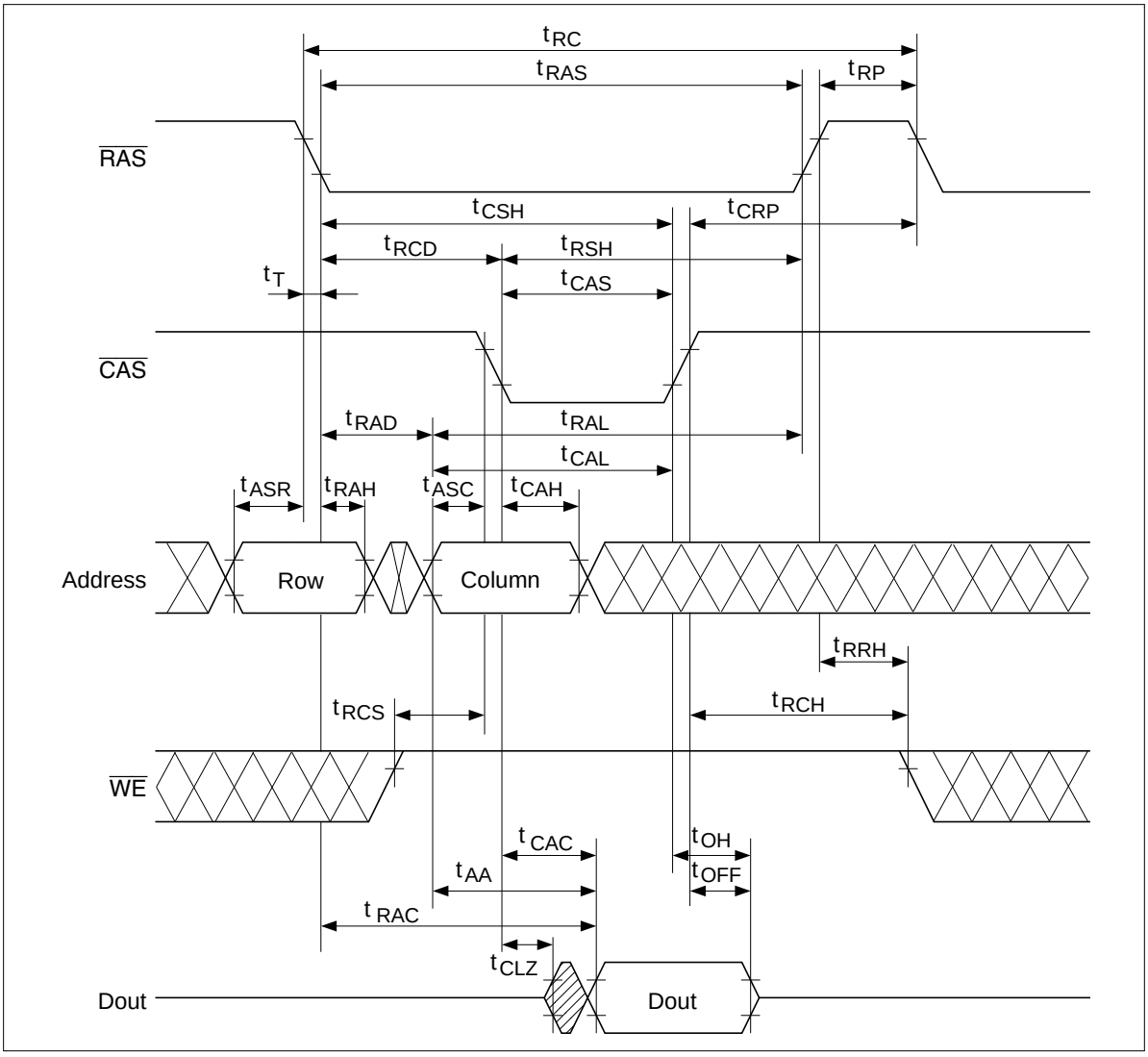
    If 16 bits are equal (all 1s or 0s), data output pin is a high state during test mode read cycle, then the device has passed. If they are not equal, data output pin is a low state, then the device has failed. Refresh during test mode operation can be performed by normal read cycles or by WCBR refresh cycles.

    To get out of test mode and enter a normal operation mode, perform either a regular $\overline{CAS}$-before-$\overline{RAS}$ refresh cycle or $\overline{RAS}$-only refresh cycle.
17. In a test mode read cycle, the value of t_{RAC}, t_{AA}, t_{CAC} and t_{CPA} is delayed by 2 ns to 5 ns for the specified value. These parameters should be specified in test mode cycles by adding the above value to the specified value in this data sheet.
18. XXX: H or L (H: V_{IH} (min) ≤ V_{IN} ≤ V_{IH} (max), L: V_{IL} (min) ≤ V_{IN} ≤ V_{IL} (max))

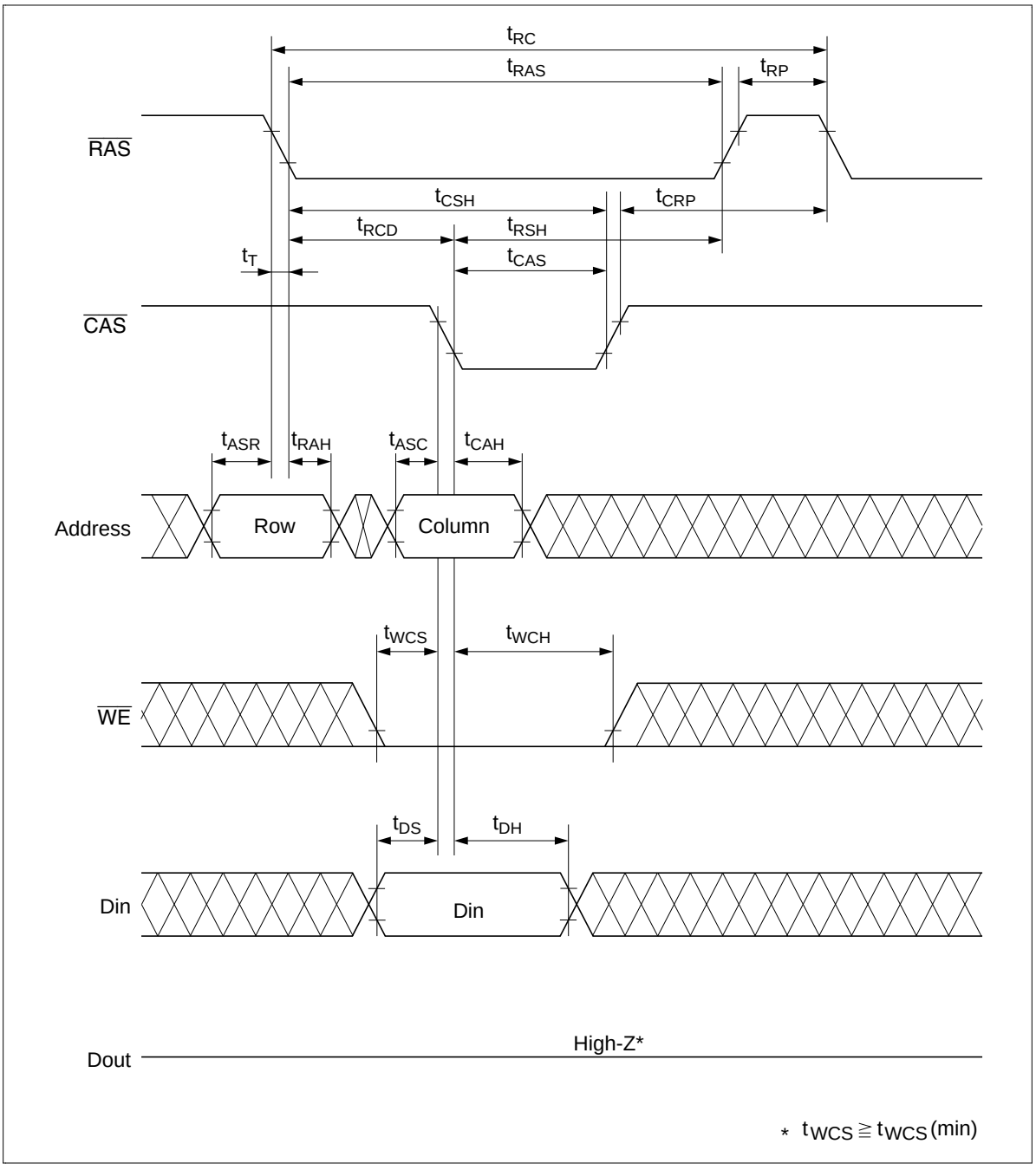
    ///////: Invalid Dout

Timing Waveforms[*18]

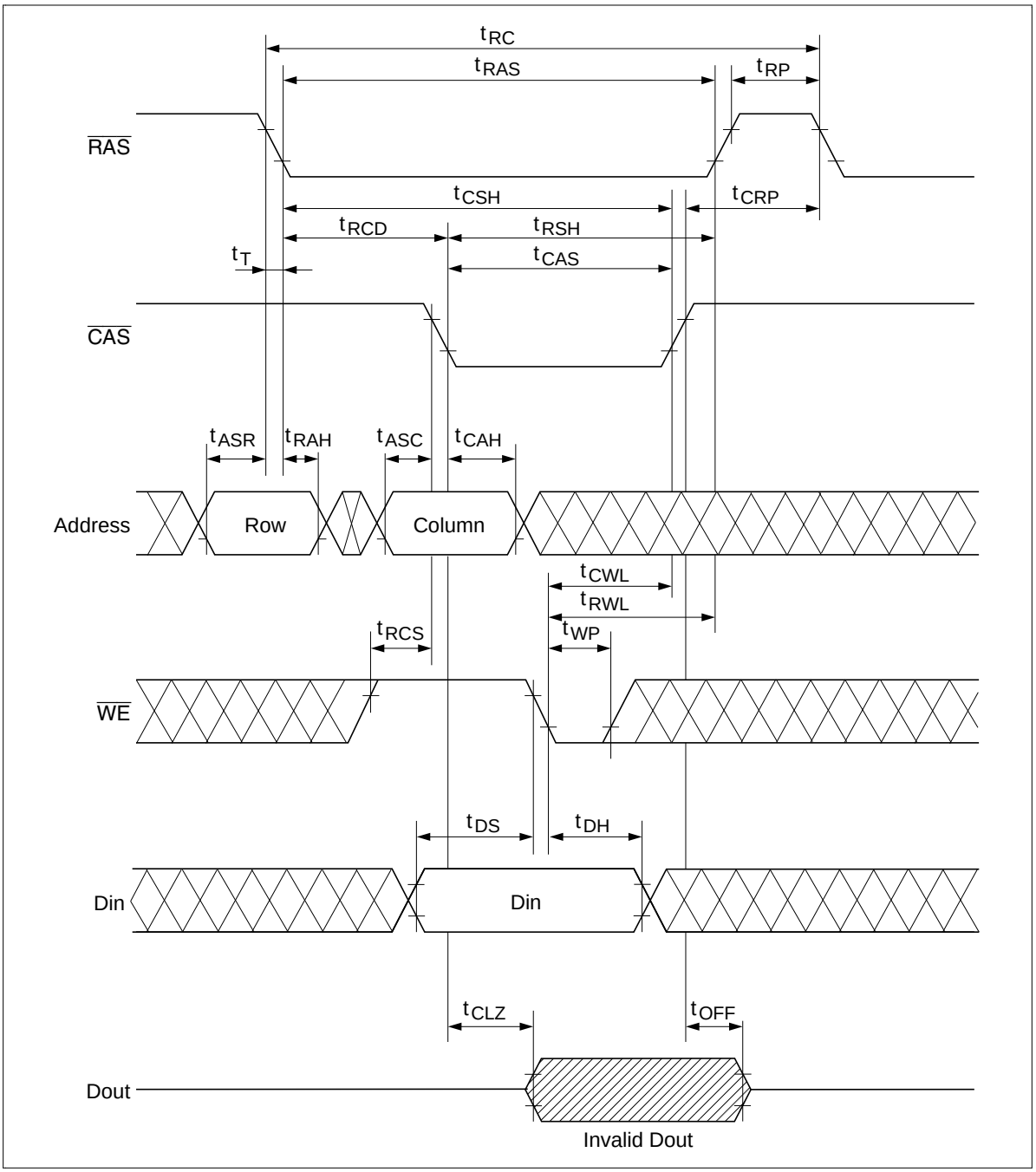
Read Cycle



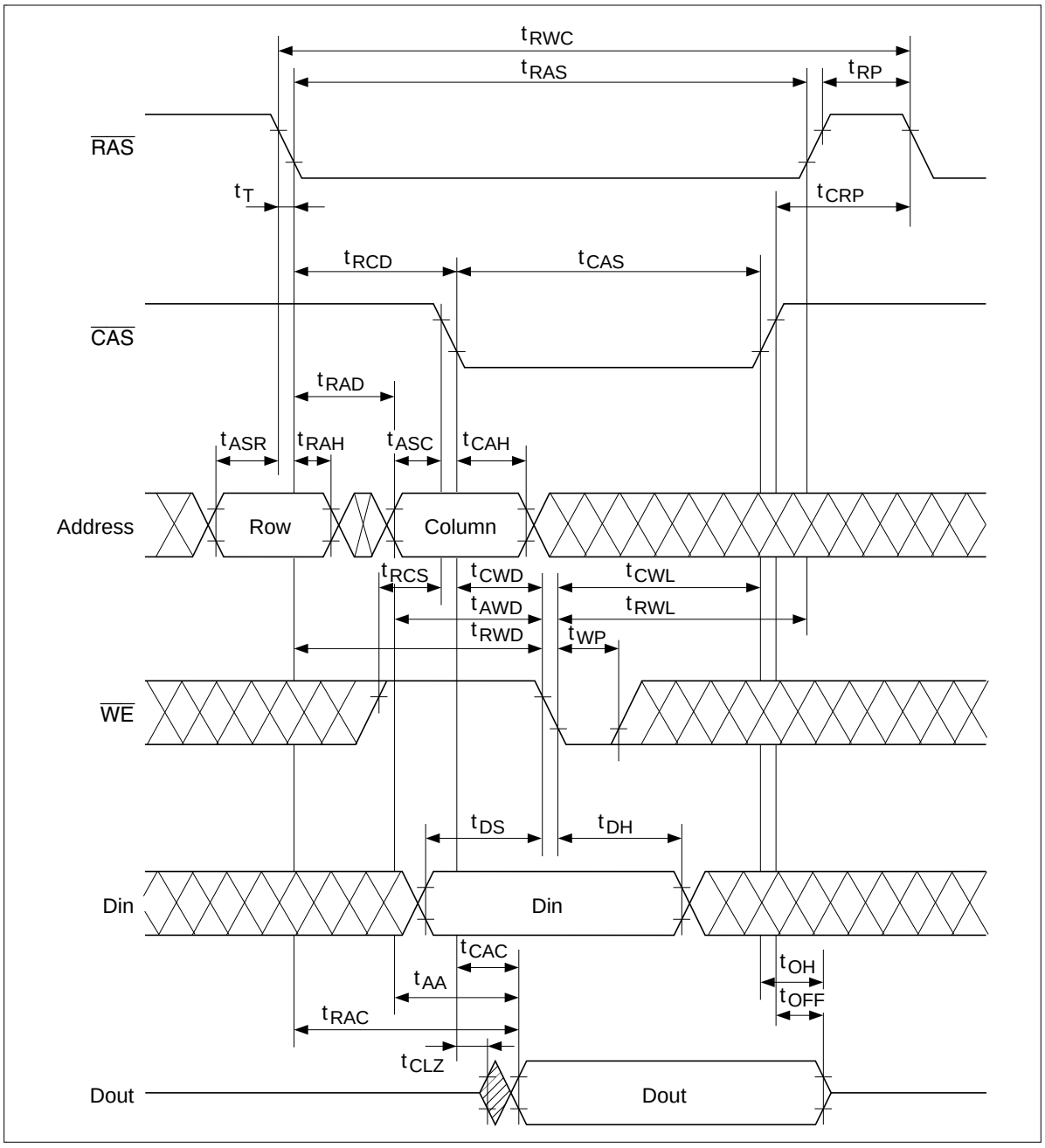
Early Write Cycle



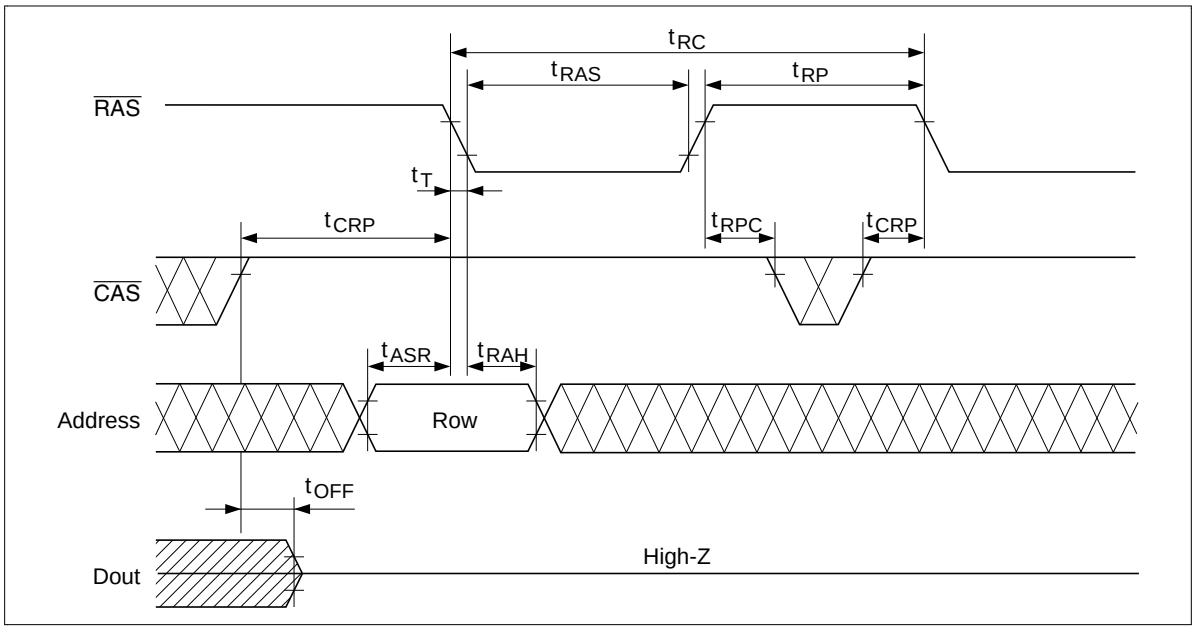
Delayed Write Cycle



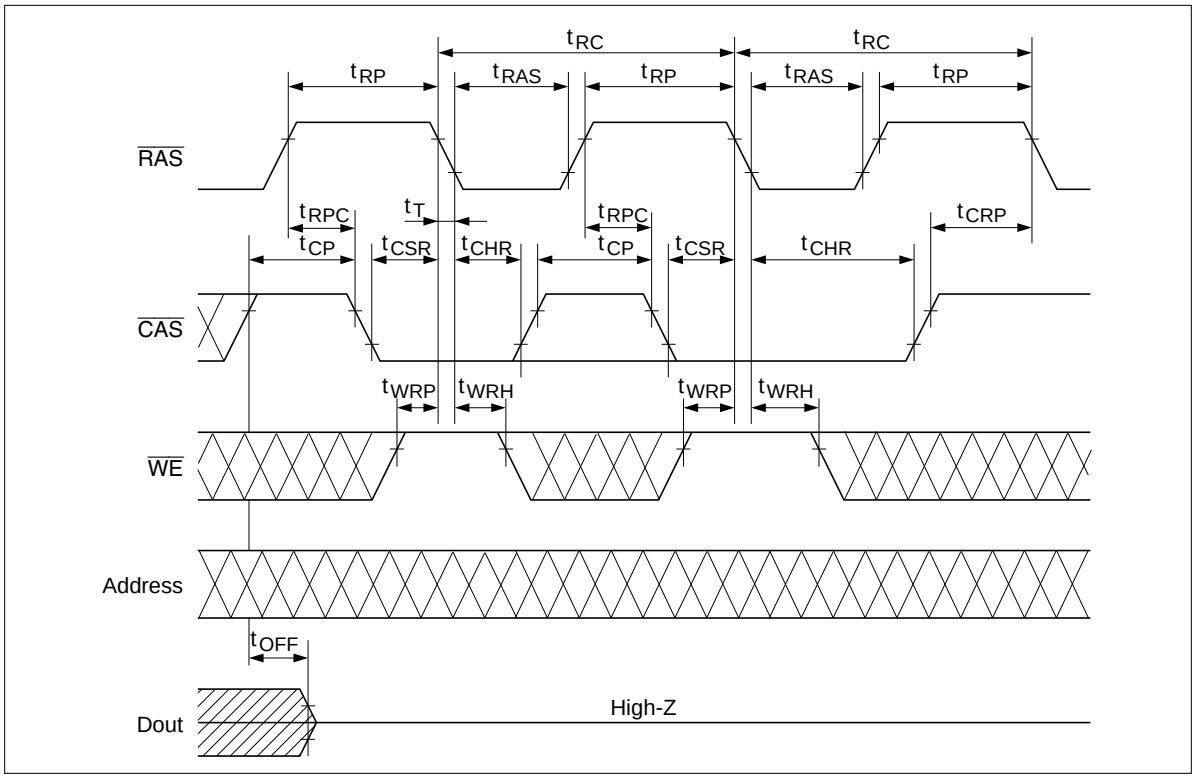
Read-Modify-Write Cycle



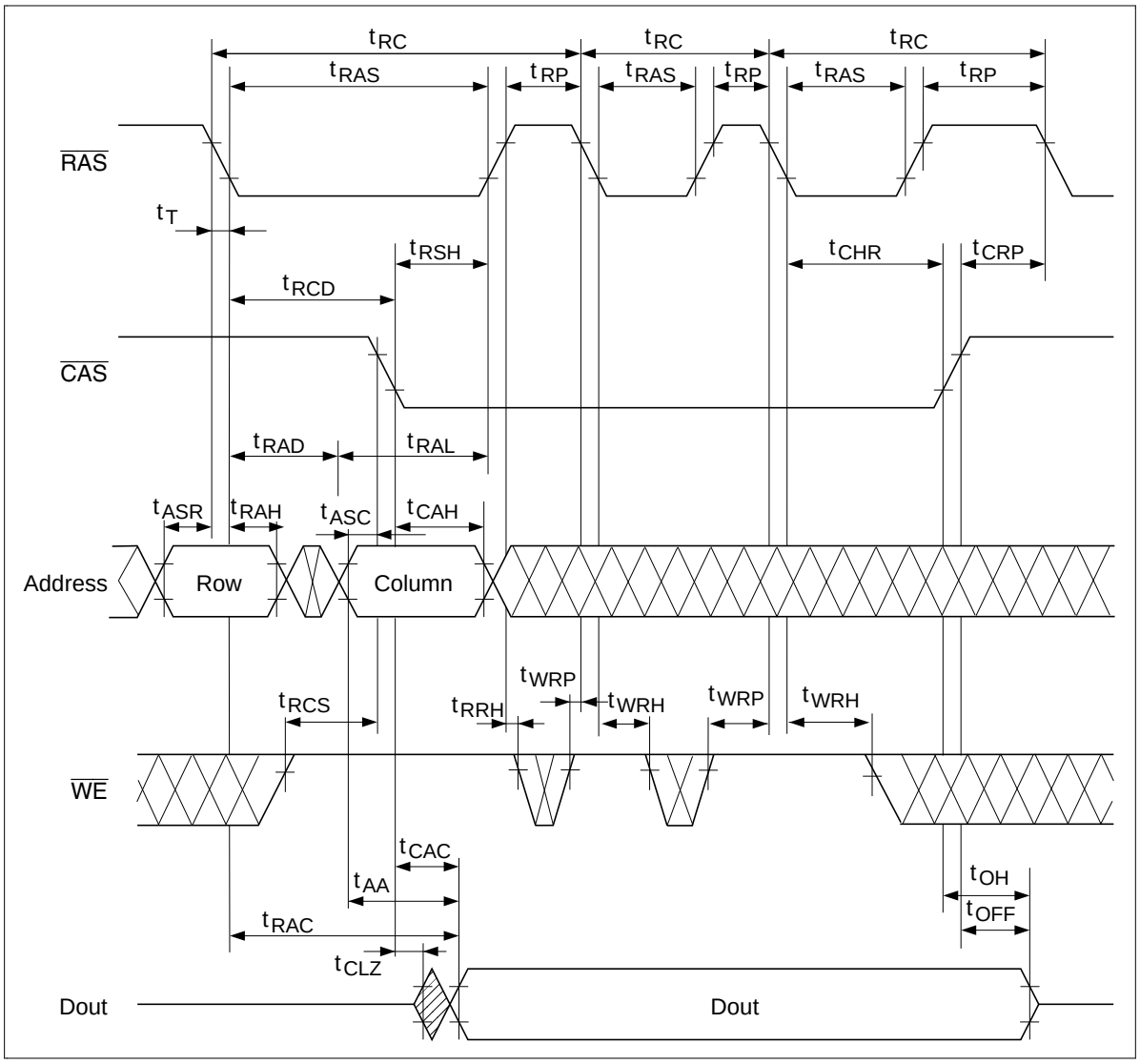
$\overline{\text{RAS}}$-Only Refresh Cycle



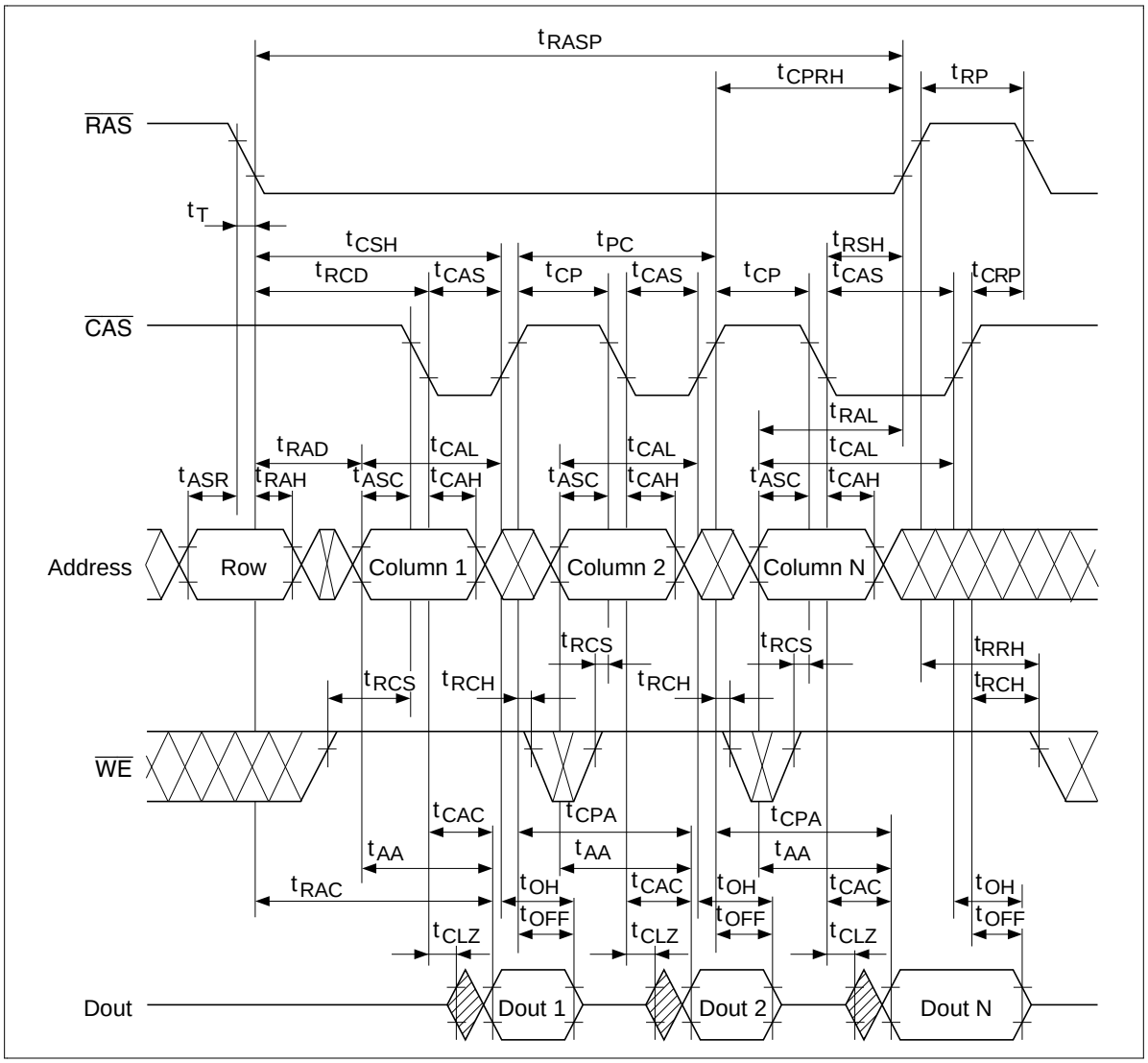
$\overline{\text{CAS}}$-Before-$\overline{\text{RAS}}$ Refresh Cycle



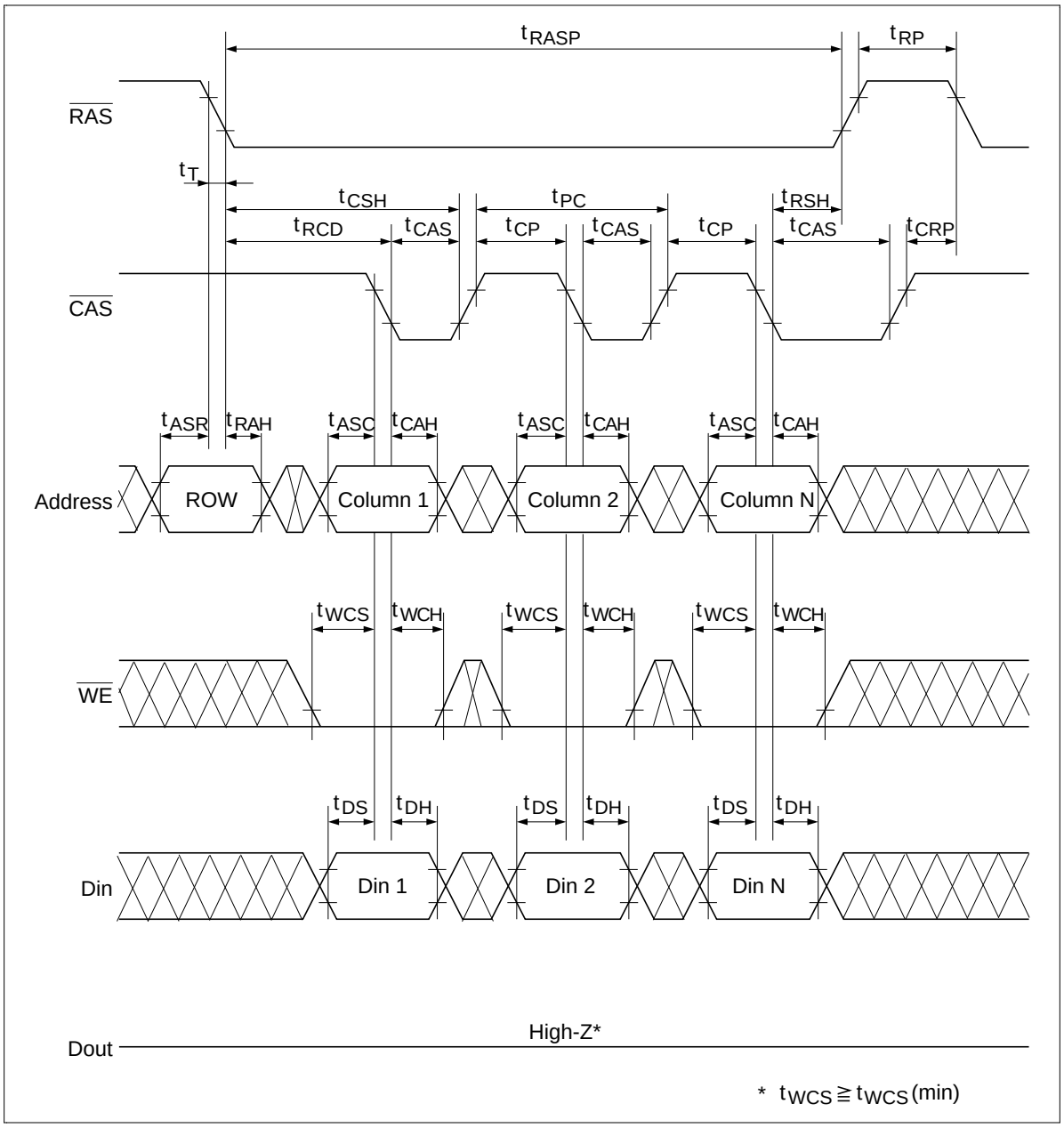
Hidden Refresh Cycle



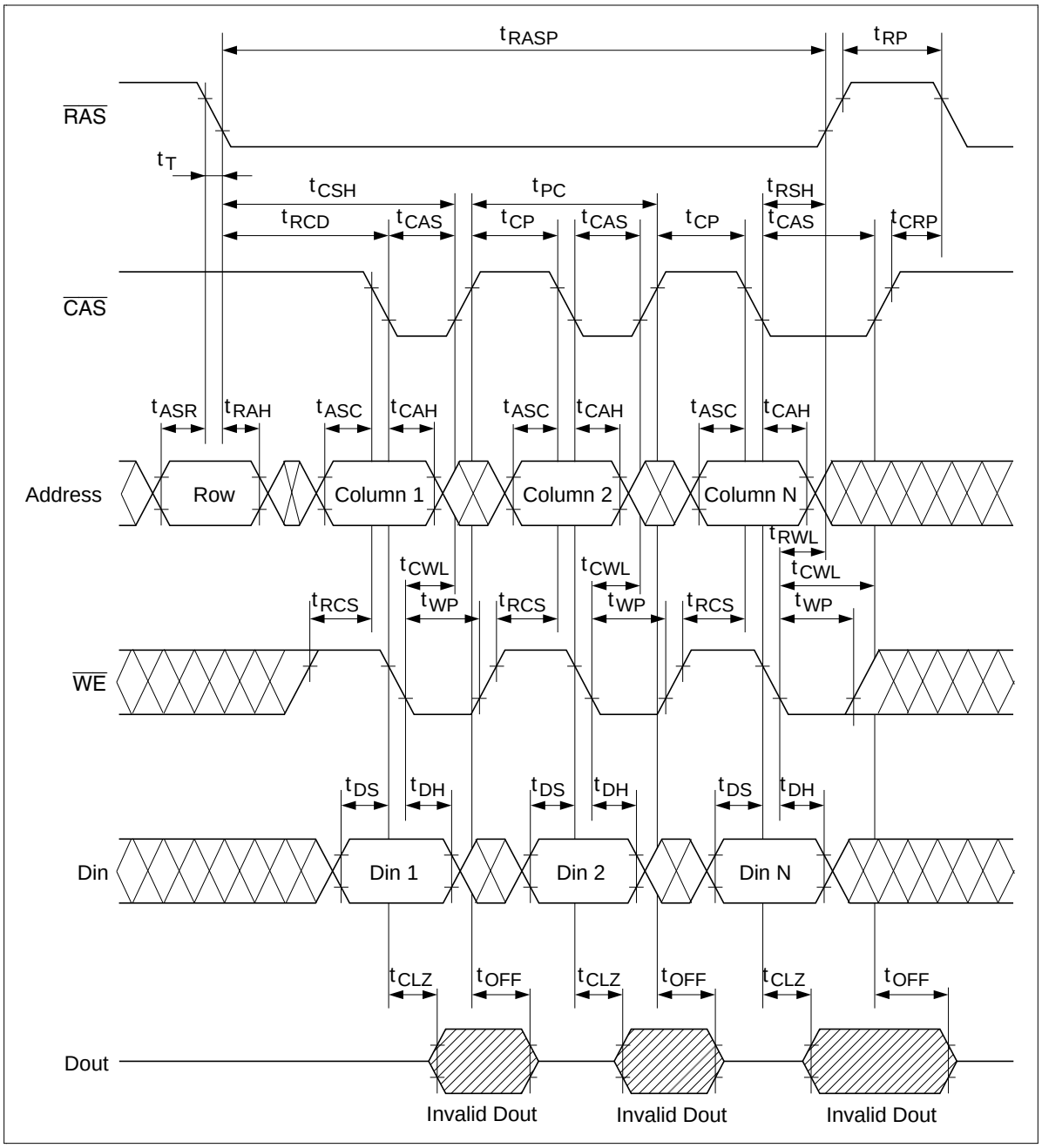
Fast Page Mode Read Cycle



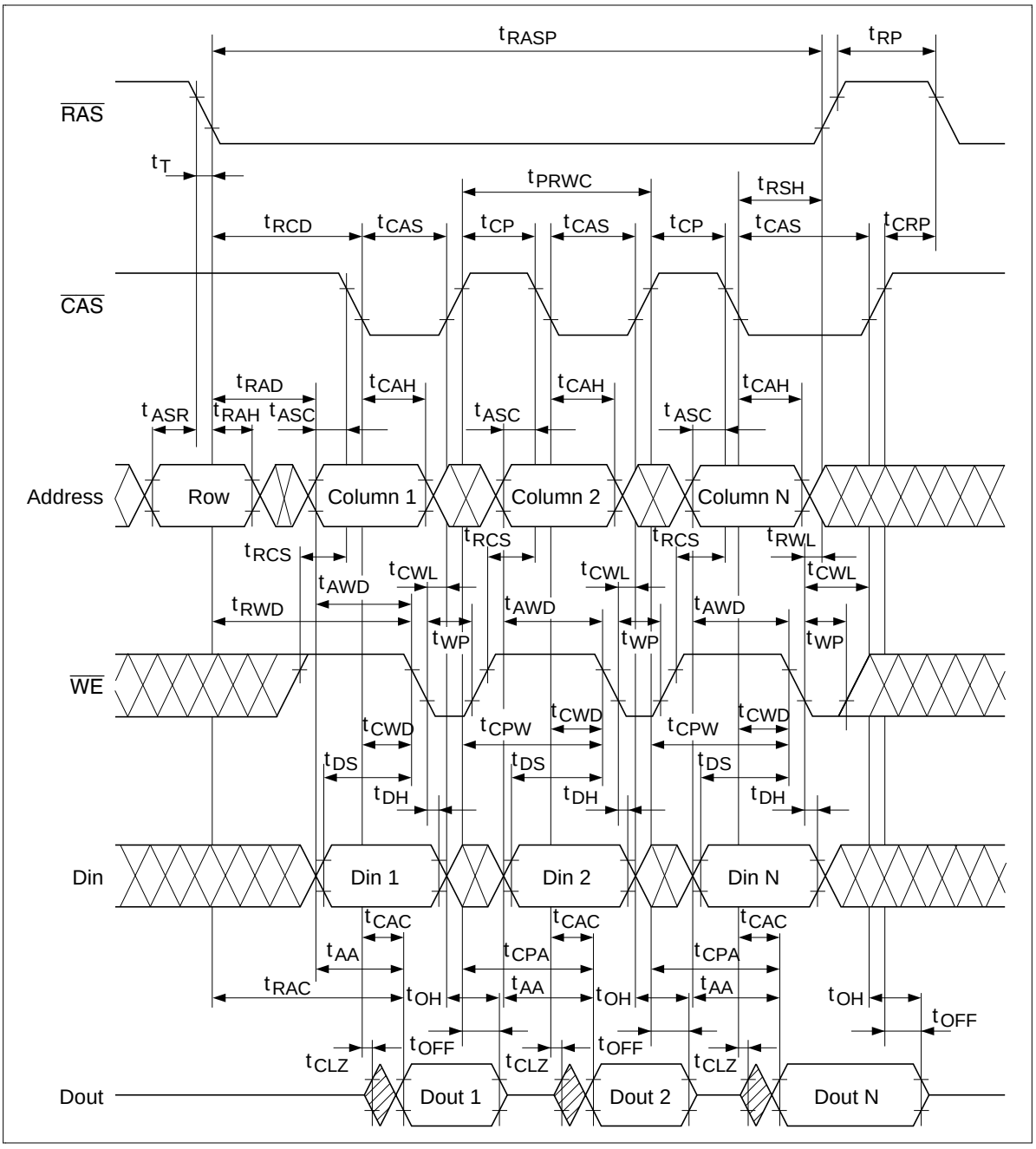
Fast Page Mode Early Write Cycle



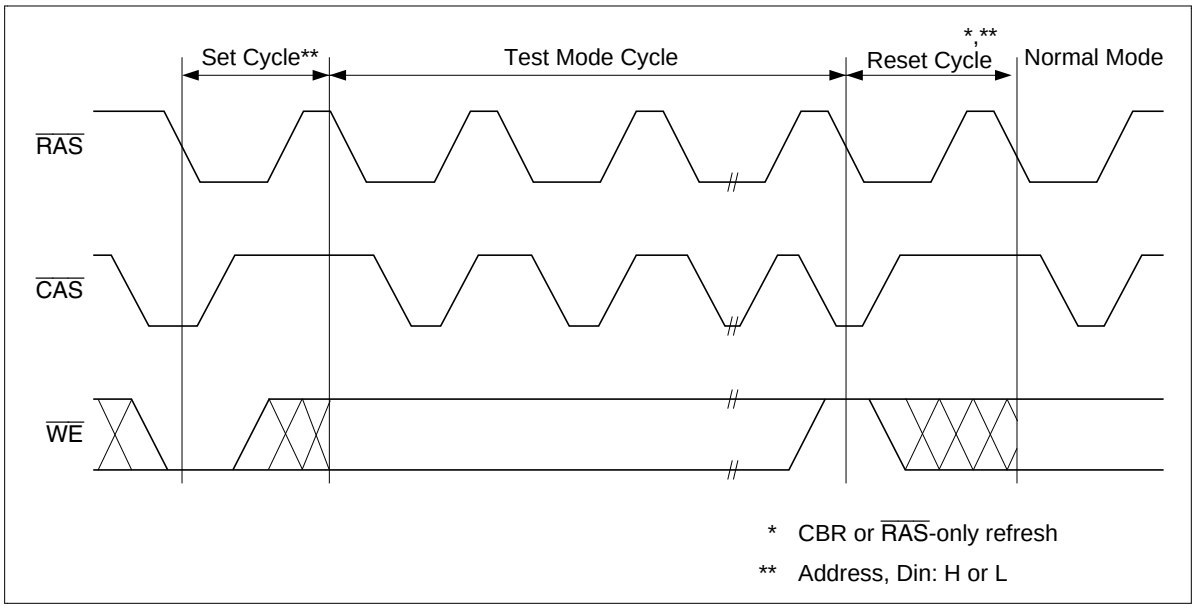
Fast Page Mode Delayed Write Cycle



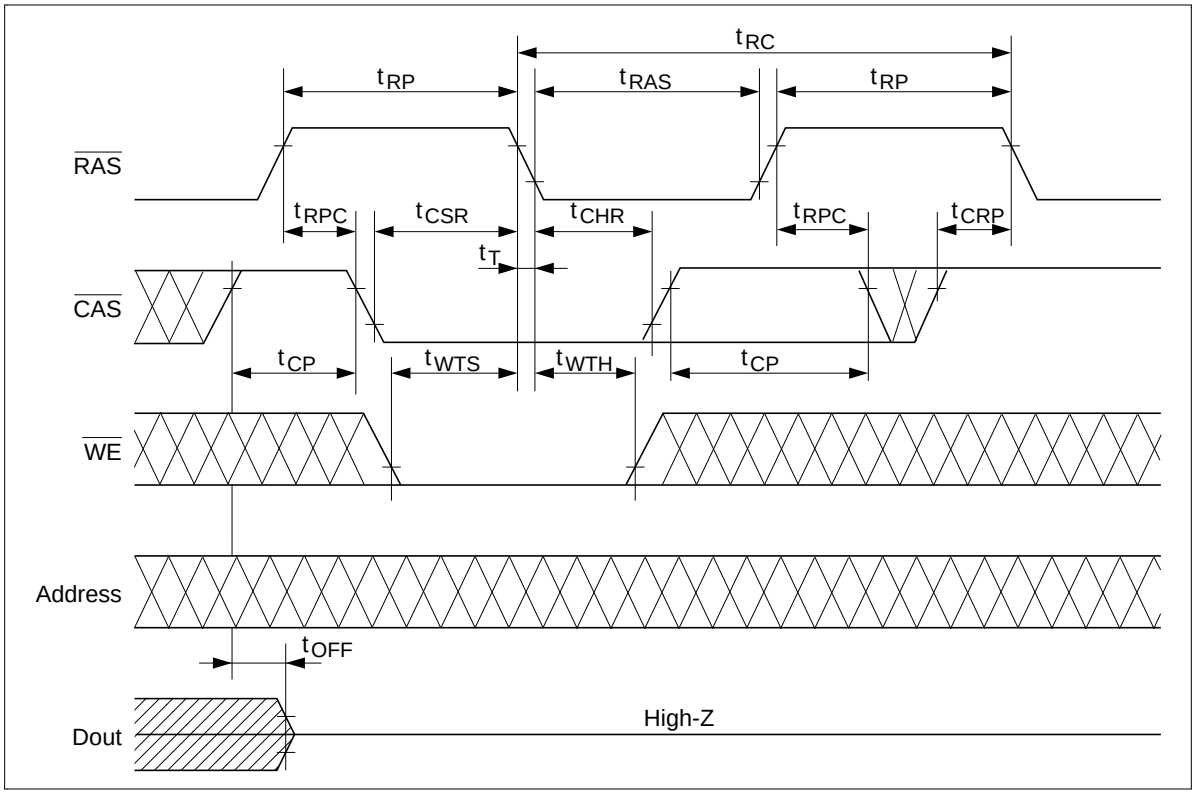
Fast Page Mode Read-Modify-Write Cycle



Test Mode Cycle*[16]



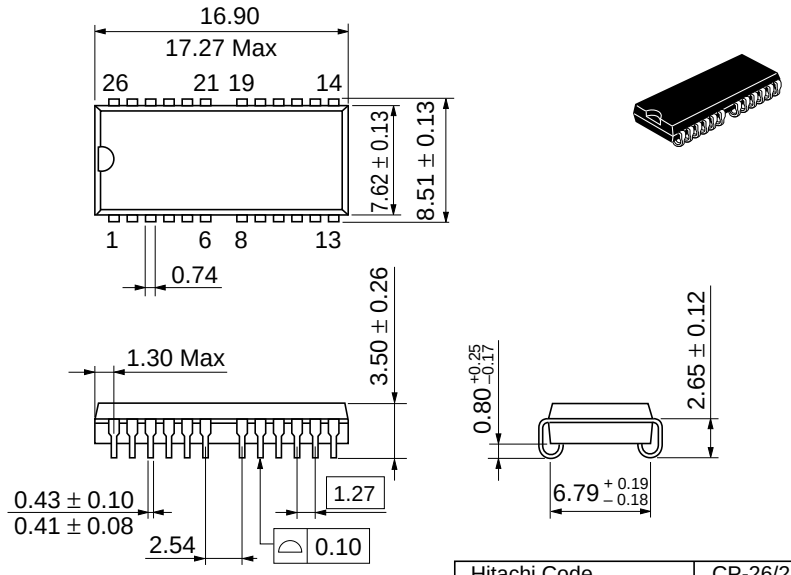
Test Mode Set Cycle



Package Dimensions

HM5116100S Series (CP-26/24DB)

Unit: mm



Dimension including the plating thickness
Base material dimension

Hitachi Code	CP-26/24DB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.8 g

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Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
1.0	Oct. 14, 1996	Initial issue	Y. Kasama	M. Mishima
2.0	Dec. 10, 1996	Addition of HM5116100-5 Series	Y. Kasama	Y. Matsuno
3.0	Feb. 27, 1997	AC Characteristics t_{RRH} min: 5/5/5 ns to 0/0/0 ns	Y. Kasama	Y. Matsuno
4.0	Jun. 24, 1997	Deletion of HM5116100-5 Series	Y. Kasama	Y. Matsuno
5.0	Nov. 1997	Change of Subtitle		